Encapsulation and protection strategies for graphenebased solution-gated field-effect transistors towards high performing neural recording

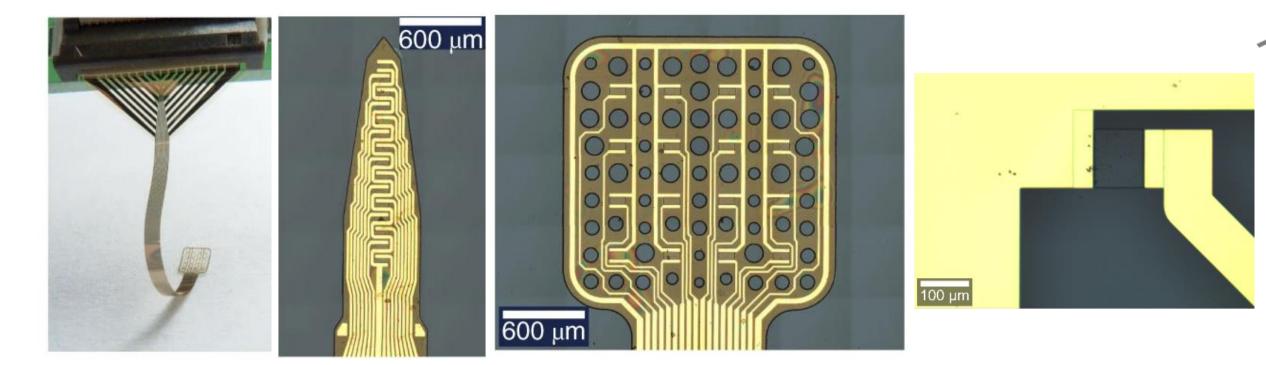
Institut Català de Nanociència i Nanotecnologia

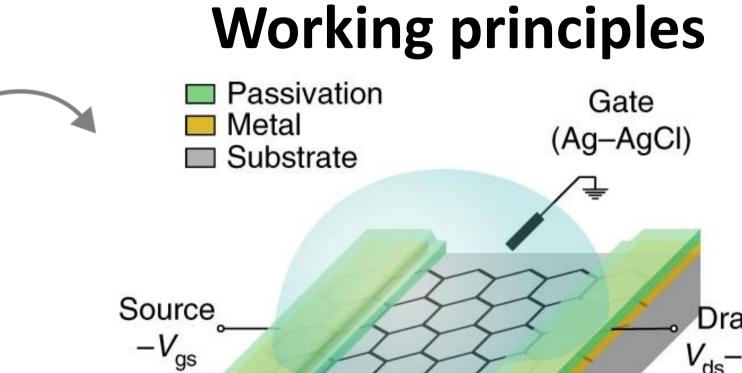
Anna Graf¹, Eduard Masvidal¹, Elena del Corro¹, Xavi Illa^{2,3}, Anton Guimera^{2,3}, Jose A. Garrido^{1,4}

¹Catalan Institute of Nanoscience and Nanotechnology (ICN2), CSIC and BIST, Campus UAB, Bellaterra, Barcelona, Spain, ²Instituto de Microelectrónica de Barcelona, IMB-CNM (CSIC), Esfera UAB, Bellaterra, Spain, ³Centro de Investigación Biomédica en Red en Bioingeniería, Biomateriales y Nanomedicina (CIBER-BBN), Madrid, Spain, ⁴ICREA, Barcelona, Spain

TOWARDS HIGH PERFORMING gSGFETs

High-resolution recording of brain activity

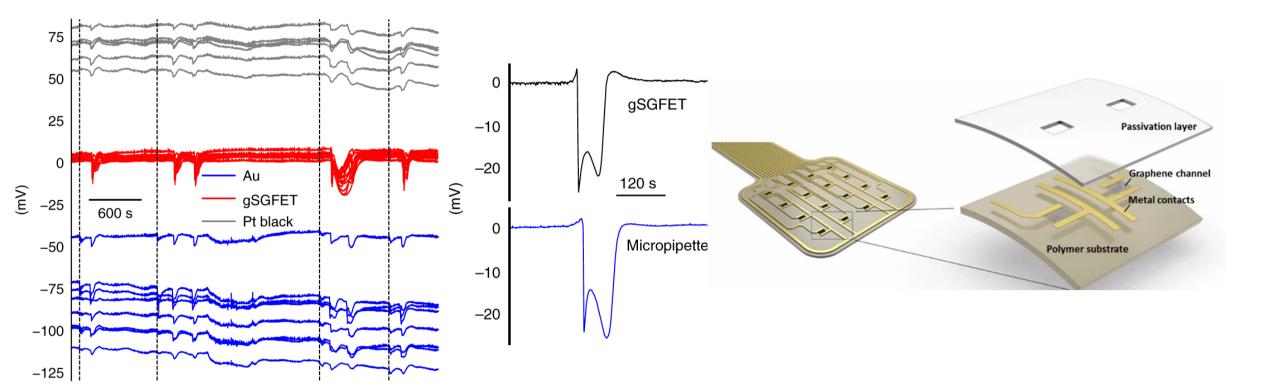




Challenges

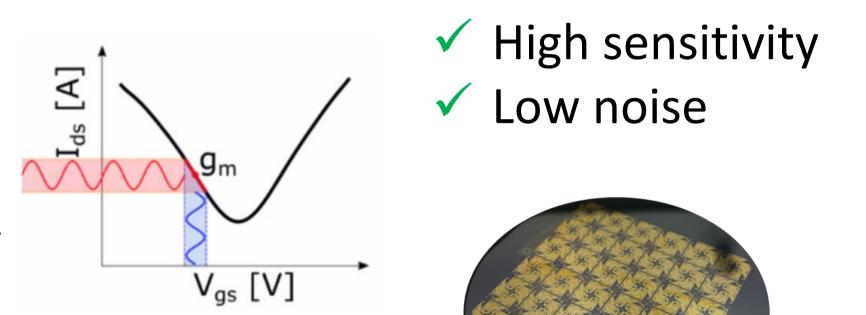
Potential not fully used!

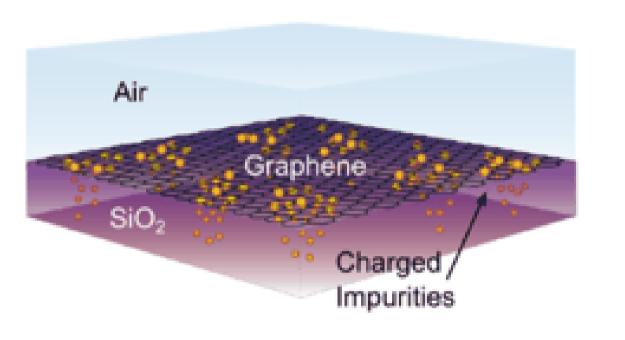
- Microfabrication contamination
- Graphene transfer residues X Substrate interaction [3]



gSGFETs allow the recording of infraslow brain activity (ISA) in a large-scale, implantable, biocompatible clinical system for applications in monitoring and treatment of neurological diseases like epilepsy or stroke [1,2].

Current is modulated by the fluctuations in the surrounding potential of graphene



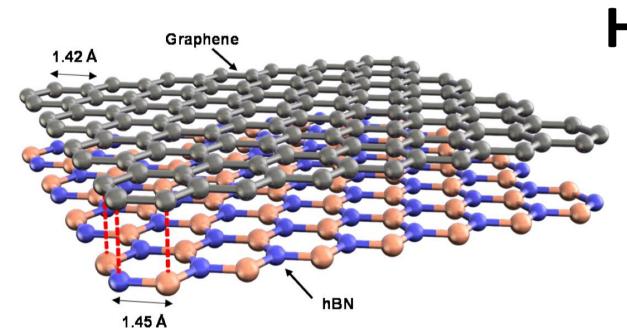


Limited electrical performance Χ

Channel protection with sacrificial layers

Towards enhanced performance and protection against fabrication residues of gSGFETs a fabrication process modification has been Metal contacts SU8 passivation proposed: Wet etching Si/SiO2 Al+Al2O3

Reducing charge scatterning from the substrate



Hexagonal boron nitride (h-BN)

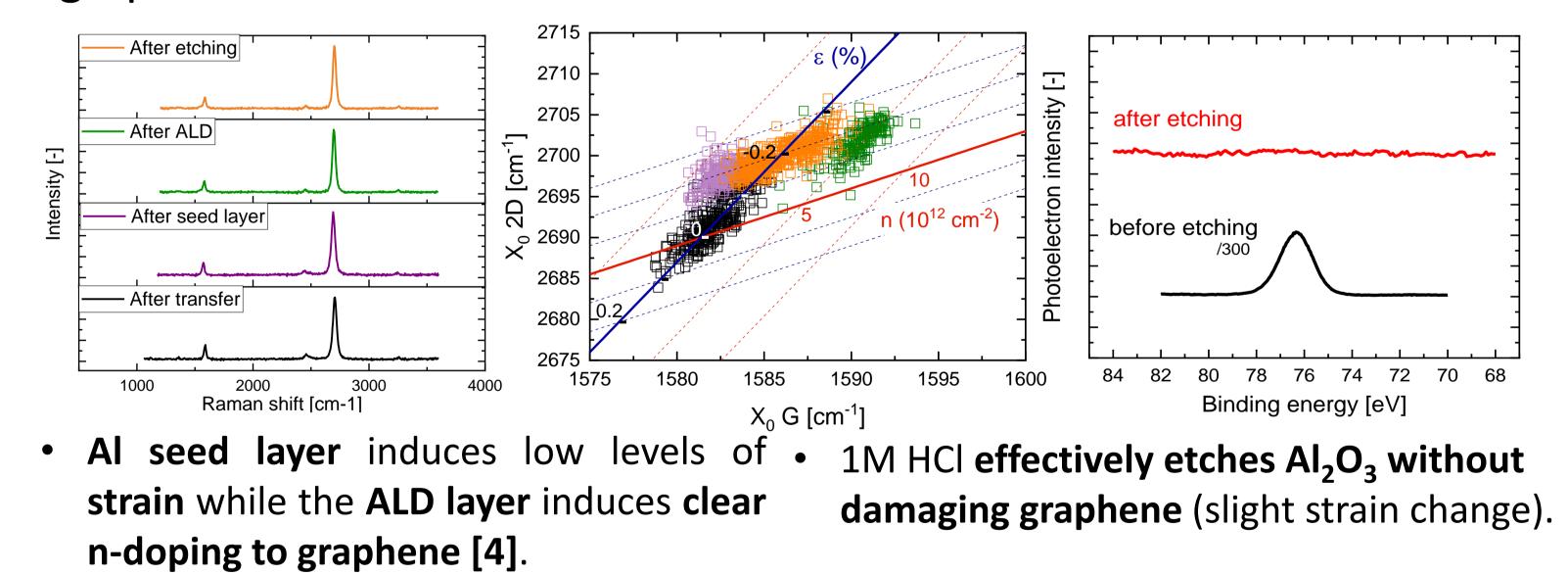
Reduces substrate interaction

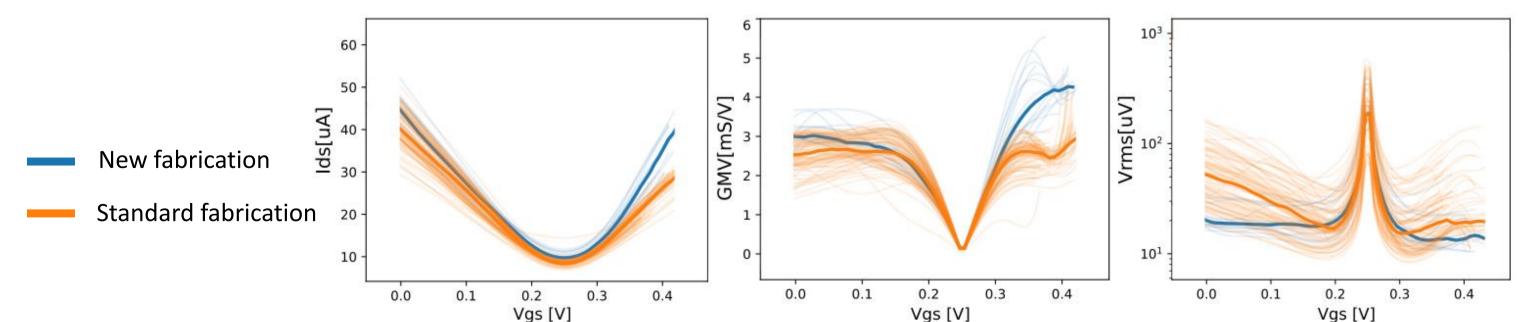
Reduces charge carrier scattering

Improves thermal management



• Low-temperature atomic layer •Residue-free removal of the layer deposition (ALD) of Al₂O₃ with at the end of the fabrication Al seed layer approach after process. graphene transfer.

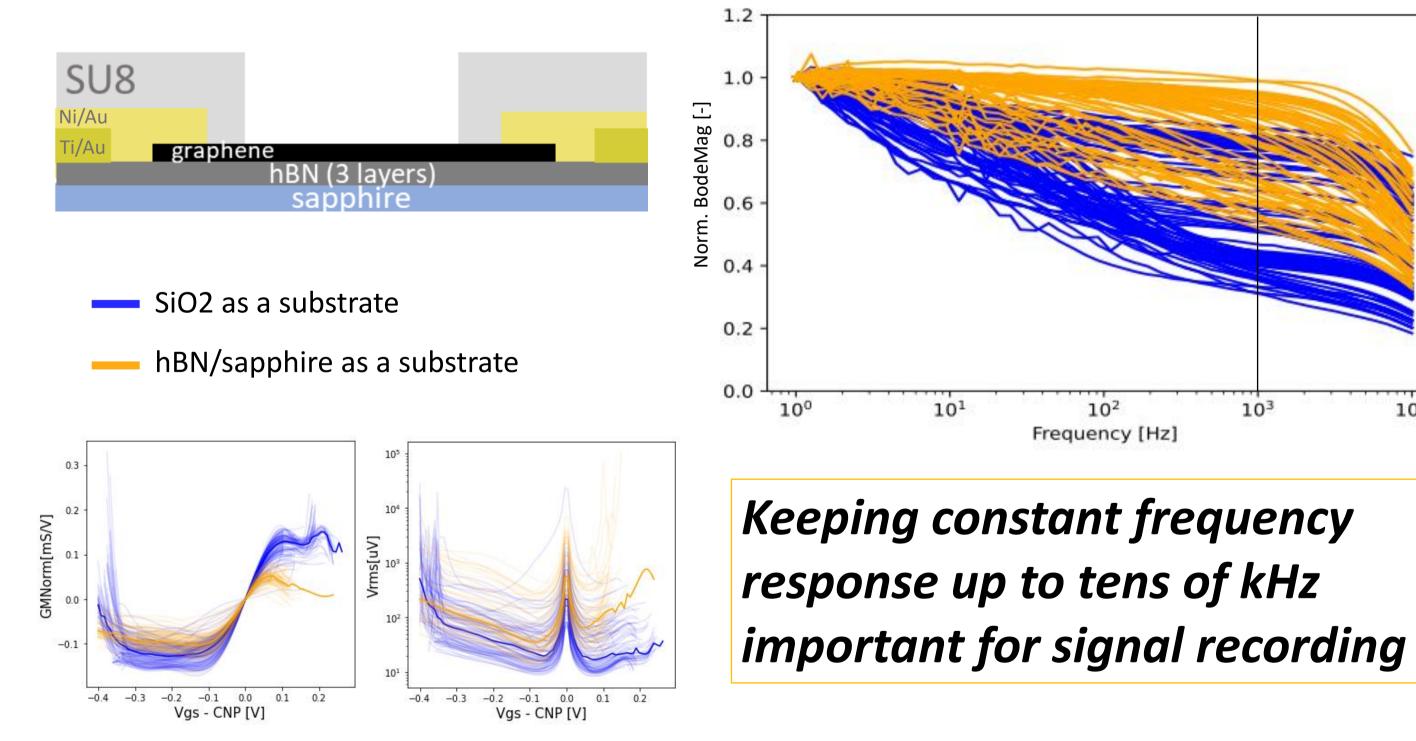




- Atomically flat surface (hBN-graphene lattice mismatch: ~1.6%)
- Crystalline structure, wide band gap (5–6 eV)
- High thermal conductivity [4]



 10^{4}



Future work will involve exploring the hBN as a decoupling layer on different substrates (SiO2, PI), benchmarking the performance, and understanding its influence on graphene-based devices.

Al₂O₃ protection demonstrates a potential in improving the electrical performance of gSGFETs and future work will focus on optimizing the fabrication process to confirm it.

CONTACT PERSON

Anna Weronika Graf anna.graf@icn2.cat **Doctoral Researcher** La Caixa INPhINIT 2022 **Advanced Electronic Materials and Devices** Catalan Institute of Nanoscience and Nanotechnology, ICN2

ACKNOWLEDGEMENTS

The ICN2 is funded by the CERCA programme / Generalitat de Catalunya, and supported by the Severo Ochoa Centres of Excellence programme, Grant CEX2021-001214-S, funded by MCIN/AEI/10.13039.501100011033

This project has received funding from the European Union's Horizon Europe research and innovation programme under grant agreement No 101136541 - GphT-BCI

A. Graf acknowledges the support of a fellowship from "La Caixa Foundation" (ID 100010434). The fellowship code is "LCF/BQ/DI22/11940031".

"la Caixa" Foundation

REFERENCES

- Masvidal-Codina, E. et al. High-resolution mapping of infraslow cortical brain activity enabled by graphene microtransistors. *Nature Mater* 18, 280–288 (2019).
- 2. Bonaccini Calia, A., et al. Full-bandwidth electrophysiology of seizures and epileptiform activity enabled by flexible graphene microtransistor depth neural probes. Nat. Nanotechnol. 17, 301–309 (2022)
- 3. Sule, N., et al. EMC/FDTD/MD Simulation of Carrier Transport and Electrodynamics in Two-Dimensional Electron Systems. Journal of Computational Electronics 12, no. 4, 563–71 (2013).
- 4. Lee, J. E., et al. Optical separation of mechanical strain from charge doping in graphene. Nat *Commun* **3**, 1024 (2012).
- 5. Ma, K.Y., Minsu, K. et al. Large-Area Hexagonal Boron Nitride Layers by Chemical Vapor Deposition: Growth and Applications for Substrates, Encapsulation, and Membranes. Accounts of Materials Research **2022** 3 (7), 748-760

